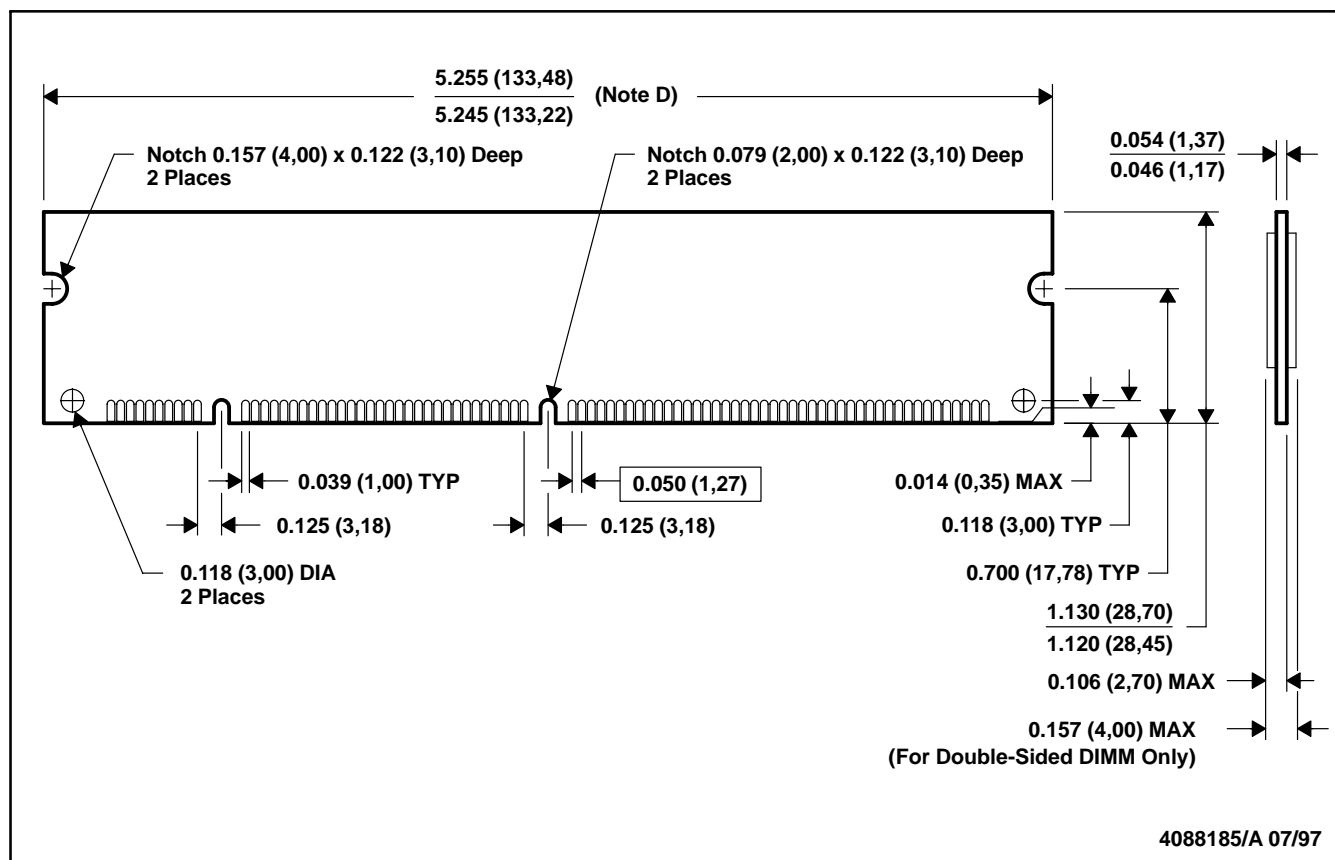


BSW (R-PDIM-N168)

DUAL IN-LINE MEMORY MODULE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MO-161
 D. Dimension includes depanelization variations; applies between notch and tab edge.
 E. Outline may vary above notches to allow router/panelization irregularities.

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